

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1-8. (cancelled)

9. (Currently amended) A method of forming an electrical interconnection by
burying powder in a trench having a bottom formed in a major surface of a substrate,
wherein the major surface is within the interior of the substrate above a lower surface of
the substrate, comprising:

applying a dispersion of the powder in a solvent onto a region including the trench;

precipitating the powder in the dispersion within the trench to bury the trench with the precipitated powder; and

polishing [[a]]the lower surface of the substrate to expose the powder buried in said trench.

10. (Previously presented) A method according to claim 9, wherein the dispersion contains a resin.

11. (Original) A method according to claim 9, wherein a portion of said powder is a glass powder.

12. (Original) A method according to claim 10, wherein a portion of said powder is a glass powder.

13-29. (Cancelled)

30. (Currently Amended) A method of forming an electrical interconnection by burying powder in a trench having a bottom formed in a major surface of a substrate, wherein the major surface is within the interior of the substrate above a lower surface of the substrate, comprising:

applying a dispersion of the powder in a solvent onto a region including the trench;

precipitating the powder in the dispersion within the trench to bury the trench with the precipitated powder,

wherein the trench includes a plug hole having a bottom formed in an upper surface of said substrate, and said precipitating includes precipitating said powder within said plug hole; and

said method further comprising removing the lower surface of the substrate until the powder buried at a bottom portion of said plug hole appears to form a chip-through plug.